_ AS		© Co	terial Compo pyright 2005. IPC, Bannocl ternational and Pan-Americ	kburn, Illinois	. All rights reserve	tion with lo		parts, the	declaration		es all lowe	r level mater	ials for	which the	item is an assembly manufacturer has
17	32-2 I.I		Web Site for Informati//www.ipc.org/IPC-1	-1752 Standa	rd		Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/No, Homogeneous				eous N	Materials and Mfg Informat			
Sup	plier Information														
Con	npany Name *	Company Unique ID			Unique ID Auth		Resp	Response Date *		Response		e Document ID			
Litte	elfuse Inc.					2		2019-06-06							
Con	tact Name *		Title - Contact		Phone - Con	Email	- Contac	t *							
Lya	C. Latoza		Global EHS Analyst		+63 430 0100		EnvR	EnvRequests@littelfuse.com							
Aut	horized Representati	ve *	* Title - Representative		Phone - Representative		Email	Email - Representative * Supplier Comments or URL for A					for Add	ditional In	formation
Jen	nilyn D. Santos		Global EHS Supervisor		+63 430 0100		EnvR	equests@	littelfus	e.com					
Requester Item Number		·	Mfr Item Number		Mfr Item Name		Effectiv	ve Date	Version	Manufacturing Site		Weight *		OM	Unit Type
	S6065KTP_TO218K		S6065KTP_218K		TRIAC 600V 65A TO218		2004-0	01-11		China		4.71187065			Each
	Alternate Recommenda	ation						Alte		ate Item Comments					•
Ма	nufacturing Proces	s Inf	formation												
Terminal Plating / Grid Array		Materi	aterial Terminal I		ase Alloy	J-STD-020 MS	-STD-020 MSL Rating		Peak Process Body		e Max Time at Peak Temp		erature Number of		f Reflow Cycles
Matte Tin (Sn)			CU Allo		•	1				<b>260</b> C		<b>30</b> sec	onds	1	
Com	ments														
The	old avamption 5 has	hoor	roplaced by Every	otion 7(c)	1 Electrical	and alactroni	c compon	onte cont	ainina la	ad in a alac	e or corar	nic other th	an dia	lactric co	ramic in canacito

	the fields in rm to a file	Export Data	Import fields from a file into this form	Import Data			Locked
RoHS	Material Co	mposition Declaration	on			Declaration Type	* Simplified
		•	• '	, .	eous material for: Lead (Pb), Mercury, Hexava lss (100 PPM) of homogeneous material for C		rominated Biphenyls (PBB),
date that Supplier n Supplier a Supplier a written ag	Supplier completes to may have relied on in grees that, at a mini reement with respec	nis form. Supplier acknowledges formation provided by others in on mum, its suppliers have provided	s that Company will rely on this co completing this form, and that Suld d certifications regarding their con and conditions of that agreement,	ertification in determining the opplier may not have independ stributions to the part, and those	priate methods to ensure its accuracy and that such informatio compliance of its products with European Union member state ently verified such information. However, in situation where s se certifications are at least as comprehensive as the certificat and/or remedies provided as part of that agreement, will be the	laws that implement the RoHS Supplier has not independently tion in this paragraph. If the Co	Directive. Company acknowledges that verified information provided by others, ampany and the Supplier enter into a
RoHS	Declaration *	4 - Item(s) does not contain R	oHS restricted substances per	the definition above except	for selected exemptions	Supplier Acceptance *	Accepted
		ared item does not contain olicable exemptions.	n RoHS restricted substan	ces per the definition at	pove except for defined RoHS exemptions, then s	elect the corresponding	response in the RoHS Declaration
Exemp	tion List Version	n EL-2006/690/EC					
	5. Lead in glass of	cathode ray tubes, electronic of	components and fluorescent tub	pes.			
	7a. Lead in high m	elting temperature type solders	(i.e. lead based solder alloys of	containing 85% by weight or	more lead).		
•							
Decla	aration Signa	ture					
					ccepted" on the Supplier Acceptance drop-do	wn. This will display th	ne signature area. Digitally sign

DN: cn=Lya C. Latoza, o, ou, email=llatoza@littelfuse.com, c=PH
Date: 2019.06.06 11:09:24 +08'00'

Supplier Digital Signature Lya C. Latoza

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

			ſ							1					
Item/SubItem	Homogeneous	Weight	Unit of Measure		Level	Substance Category		Substance	CAS	Exempt		Unit of Measure	Tolerance		PPM
Name	Material		weasure									weasure	-	+	
TRIAC 600V 65A TC	Heatsink/Lead fr	3.2232	g		Supplier	CuFEP		Copper (Cu)	7440-50-8		3.217075	g			
								Iron (Fe)	7439-89-6		0.004834	g	Ш		
								Phosphorus (P)	7723-14-0		0.001289	g			
	Outside Lead Fir	0.05997	g		Supplier	Tin (Sn)		Tin (Sn)	7440-31-5		0.05997	g			
	Die attach (Sold	0.0183	g		Supplier	Pb95Sn5		Tin (Sn)	7440-31-5		0.000915	g			
					A	Lead/Lead Compound		Lead	7439-92-1	7a. Lead	0.017385	g			950,0
	Die attach (Sold	0.015	g		Supplier	Pb88Sn10Ag2		Tin (Sn)	7440-31-5		0.0015	g			
								Sliver	7440-22-4		0.0003	g			
					A	Lead/Lead Compound		Lead	7439-92-1	7a. Lead	0.0132	g			880,0
	Die Attach (Sold	0.012	g		Supplier	Pb90Sn10		Tin	7440-31-5		0.0012	g			
					A	Lead/Lead Compound		Lead	7439-92-1	7a. Lead	0.0108	g			900,0
	Chip	0.02111	8g		Supplier	Silicon (Si)		Silicon (Si)	7440-21-3		0.020533	g			
					В	Nickel (external applic		Nickel	7440-02-0		0.000585	g			
	Chip Passivation	0.00092	ŧg		Supplier	SiO2		SiO2	7631-86-9		0.000462	g			
					Supplier	PbO		PbO	1317-36-8	5. Lead ii	0.000411	g		-	444,4
					Supplier	Al2O3		Al2O3	1344-28-1		0.000010	g			
					Supplier	Boron		Boron	7440-42-8		0.000012	g			
					Supplier	Oxygen		Oxygen	7782-44-7		0.000028	g			
	Ceramic Substra	0.2482	g		Supplier	Ceramic		AI2O3	1344-28-1		0.238272	g			
		•						Misc., not to declare	SYSTEM		0.009928	g			
	Clip	0.06175	g		Supplier	CuO		Copper	7440-50-8		0.061738	g			
								Oxygen	7782-44-7		0.000018	g			
	Molding Compo	1.0514	g		Supplier	Moulding Compound		Epoxy resin	SYSTEM		0.21028	g		T	
						1								-	

<sup>\*</sup> Required Field

Phenol resin	SYSTEM	0.094626	g		
non- brominated flame	SYSTEM	0.21028	g		
Carbon black	1333-86-4	0.010514	g		
Silica Fused	60676-86-0	0.5257	g		